





Certificate of Registration

OUALITY MANAGEMENT SYSTEM - EN 9100:2018 AND ISO 9001:2015

This is to certify that:

Micross Components Limited

2-4 Hellesdon Park Road

Drayton High Road

Norwich NR6 5DR

United Kingdom

Holds Certificate Number: FS 763245

and operates a Quality Management System, with a Multiple site certification structure, which complies with the requirements of EN 9100:2018 (technically equivalent to AS9100D and JISQ 9100:2016) and ISO 9001:2015 and is assessed in accordance with EN 9104-001:2013 for the following scope:

The test and qualification of semi-conductor devices and the assessment of unencapsulated add-on components, the design, development, manufacture, and test, including sub-contract manufacture of thick and thin film hybrid and PCB assemblies and associated sub-assemblies, microelectronic packaging, for application in market sectors that include, Defence, Aerospace, Space, Telecoms and Industrial.

For and on behalf of BSI:

Matt Page, Managing Director Assurance - UK & Ireland

Original Registration Date: 2008-11-25

Reissue Date: 2023-11-22 Expiry Date: 2026-11-21

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aerospace sector certification scheme

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Issue Date: 2023-11-22

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Certificate No: FS 763245

Location Registered Activities

Micross Components Limited*

2-4 Hellesdon Park Road

Drayton High Road

Norwich

NR6 5DR

Test and qualification of semiconductor devices and the assessment of un-encapsulated add-on components, for application in market sectors that include, Defense, Aerospace, Space, Telecoms and Industrial.

Technograph Microcircuits Ltd Unit A1-A4 Railway Triangle Walton Road Drayton Portsmouth PO6 1TN United Kingdom

United Kingdom

The design, development, manufacture, and test, including sub-contract manufacture of thick and thin film hybrid and PCB assemblies and associated sub-assemblies. Microelectronic packaging.

Original Registration Date: 2008-11-25 Issue Date: 2023-11-22 Reissue Date: 2023-11-22 Expiry Date: 2026-11-21

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^{* =} Central Function